



LINXENS

CONNECTING YOU TO SUCCESS

SMART-DC INLAY

SMART-DC UHF



Today's state-of-the-art contactless inlay technology has significantly improved the complete value chain for eID documents, from the chip supplier via the inlay manufacturer to the document producer.

New features in next-generation eID documents are enabled by ultra-thin, durable, flexible and homogeneous flat inlay characteristics.

LINXENS's latest SMART-DC technology connects bare micro-controller chips directly to the antenna. A process necessary to fulfill the requirements of highly durable, secure and reliable eID documents.

Bonding the chips to the antenna with a pure metallic interconnection, using LINXENS's wafer processing and patented palladium bumping technology, avoids using any material sensitive to aging.

LINXENS's SMART-DC UHF inlay offers leading performance and memory options for electronic driver's license (eDL), electronic Residence Permit (eRP) and Border Crossing applications.

Overview

Operating Frequency

860-960 MHz

Operating Temperature

-25°C to +50°C

Integrated Circuit (IC)

ICs from leading suppliers

Material

PC

International Standards

- ISO 18000-6C

Application Area

- eDriver's License
- eResidence Permit
- Border Crossing

Features

- Printed Antenna Technology
- Palladium Bumping




LINXENS

CONNECTING YOU TO SUCCESS

SMART-DC INLAY

SMART-DC UHF

Antenna	Operating Frequency	Sheet format	Thickness	Available IC
	860-960 MHz	Max. 510 x 680mm	approx. 200µm	EM, Impinj, NXP

Additional memory, protocol and product configurations are available upon request.
Note: Pictures are for illustration only and are not to scale.